

Tervetuloa O-johtavaan

O-Leading pyrkii olemaan yhden luokan ratkaisukumppanisi EMS-toimitusketjussa, mukaan lukien piirilevyjen suunnittelu, piirilevyjen valmistus ja piirilevyjen kokoaminen (PCBA). Tarjoamme joitain edistyneimmistä piirilevyteknikoista, mukaan lukien HDI-piirilevyt, monikerroksiset piirilevyt, jäykät ja joustavat piirilevyt. Voimme tukea prototyypin nopeasta kääntämisestä keskisuurten ja massatuotantoon.

Yleisesti ottaen globaalit asiakkaamme ovat erittäin vaikuttuneita palveluistamme: nopea vastaus, kilpailukykyinen hinta ja sitoutuminen laatuun. Arvokkaamman teknisen palvelun ja kokonaisratkaisun tarjoaminen on O-tapa edetä.

Tulevaisuuden näkökulmasta O-johtava keskittyy aina elektroniikan valmistustekniikan innovaatioihin ja kehitykseen ja pyrkii jatkuvasti PCB:n ja PCBA:n keskitettyyn palveluun tarjoamaan ensiluokkaisia palveluita ja luomaan enemmän arvoa asiakkaillemme.

NOLLAA NÄMÄ LISÄTIETOJA [OEM LED nauhat pcb valmistaja Kiina](#)

Tuotteen Kuvaus

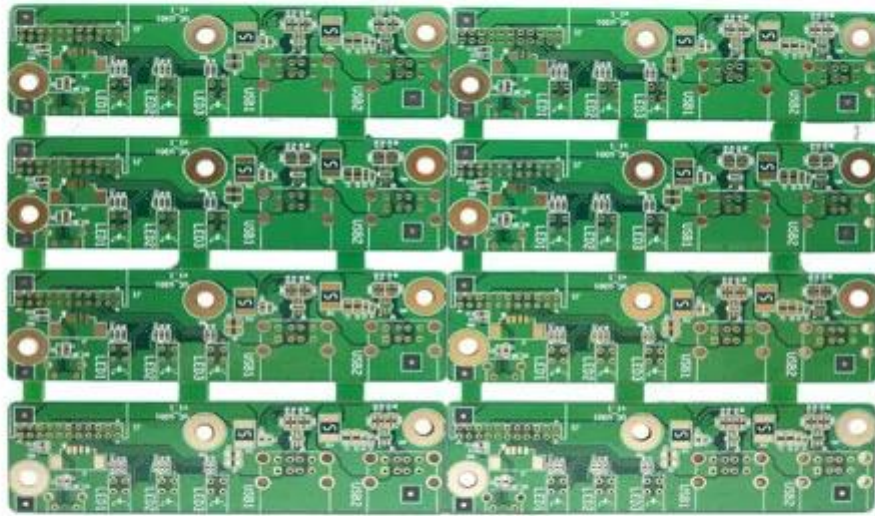
Lähtöisin	Guang dong, Kiina (manner)	Tuotenimi	O-Johtavat
Pohjamateriaalia	FR-4, alumiini	Kuparin paksuus	0.5oz-5oz
Min. Reiän koko	0.2mm	Min. Viivan leveys	0.2mm
Pinnan viimeistely	upotuskulta, OSP, lyijytön HASL	Levyn paksuus	0.1-5mm
sovellettavissa	led, matkapuhelin, ilmastointilaitteet, pesukoneet	merkki	Teollisuuden ohjaus pcb
todistukset	ISO9001, UL, RoHS, SGS	Q / CTN	10PCS-100PCS
paino	0,01-5 kg	MOQ	10kpl
Mallinumero	voimapankki pcb-kokoonpano pcb-a-valmistaja	Min. Riviväli	0.2mm
väri-	sininen, punainen, vihreä, musta.väri	hinta	\$ 0,1- \$ 10
desigh tyyppi	asiakasvaatimus	koko	0.01m3-10m3

Tuotantokyky

16 vuoden ammattimainen OEM-piirilevyjen valmistus

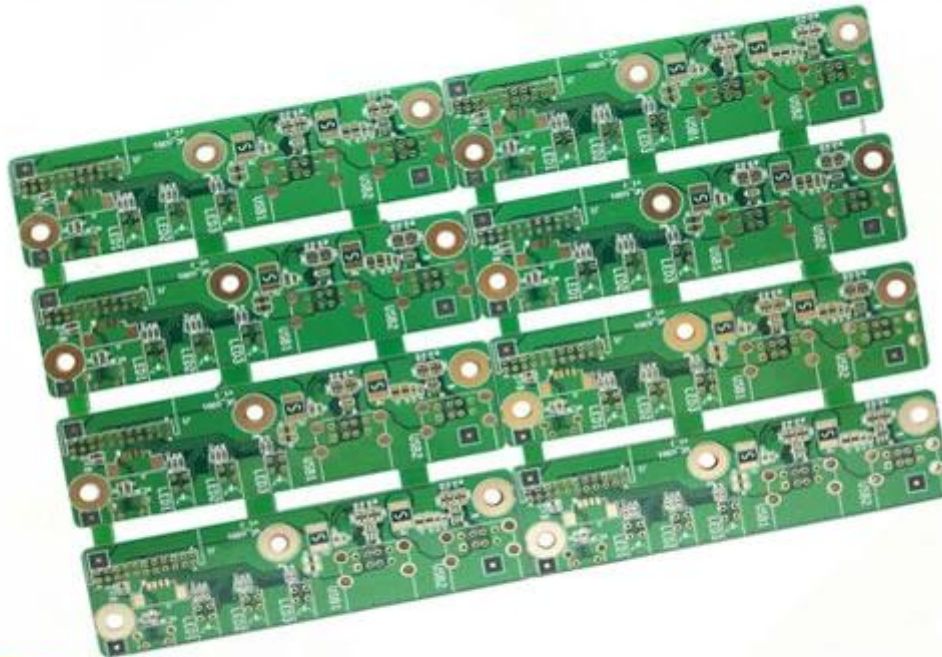
erä	2014		2015 ~ 2016		2017 ~ 2018	
	tilavuus	Näyte	tilavuus	Näyte	tilavuus	Näyte
Kerrostien lukumäärä	32	42	38	44	42	48
Pienin viiva / tila (µm)	50/50	40/45	40/45	40/40	35/40	35/35

Min. Reikä halkaisija (mm)	0,15	0,10	0,15	0,10	0,15	0,10
Kuvasuhde PTH: sta	14: 1	16: 1	16: 1	18: 1	18: 1	20: 1
N + C + N	4 + C + 4	5 + C + 5	5 + C + 5	6 + C + 6	5 + C + 5	6 + C + 6
Mikä tahansa kerrosten kytkentä	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6	5 + 2 + 5	6 + 2 + 6
Levyjen täyttö kautta	JOO	-	JOO	-	JOO	-
Min. ytimen paksuus (pois lukien kupari) (µm)	50	40	40	30	40	30
Min. Laserporan halkaisija (µm)	75	65	65	50	50	40
Via haudattu reikä / pinottu kautta	JOO	-	JOO	-	JOO	-
materiaali	FR4, Megtron, Nelco, Rogers, Heavy Copper jne.					
Sulautettu kondensaattoriipiiri	JOO	-	JOO	-	JOO	-
Pintaprosessi	Lyijytön HASL, ENIG, OSP, upotettava hopea, upotettava tina, Flash-kulta, kulta sormenpäällyste, valikoiva kova kullattu, Kuorittava juotosmaski, hiilimuste					





www.o-leading.com



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[oem pcb-levyjen valmistaja Kiina](#)

Tiimimme



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT







Test Report

No. SZXEC1900530401

Date: 30 Mar 2019

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O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP) , Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP) , and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory



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Test Report

No. SZXEC1900530401

Date: 30 Mar 2019

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Test Results :

Test Part Description :

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green"PCB"

Remarks :

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = Method Detection Limit
- (3) ND = Not Detected (< MDL)
- (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test item(s)	Limit	Unit	MDL	Q/Z
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max		Max		Meets		C
	Min	Min			Area	Solder	Oper	Flame	UL796		
	mm(in)	mm(in)			Diam	Limits	Temp	Class	DSR		
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Prosessin kyky

Piirilevyjen tuotantokapasiteetit

Kerros määrä: 1-kerros-32-kerros

Valmiiden kuparien paksuus □ 1 / 3oz-12oz

Min Rivin leveys / etäisyys sisäinen □ 3,0mil / 3,0mil

Min Rivin leveys / välinen etäisyys: 4,0mil / 4,0mil

Suurin kuvasuhde: 10: 1

Levyn paksuus □ 0,2-5,0 mm

Paneelin enimmäiskoko (tuumaa): 635 * 1500 mm

Poratun reiän vähimmäiskoko: 4mil

PI-reikätoleranssi: +/- 3mil

Blind / Buried Vias (All-tyypit): YES

Täyttämällä (johtava, johtamaton): KYLLÄ

Pohjamateriaali: FR-4, FR-4korkean painon halogeeniton materiaali, Rogers, alumiininen pohja,polyimidi,
Raskas kupari

Pintakäsittelyt: HASL, OSP, ENIG, HAL-LF, hopea,Lummersion Tina, kultaiset sormet, hiilimuste

SMT-tuotantokapasiteetit

Piirilevymateriaali: FR-4, CEM-1, CEM-3, alumiinipohjainen levy

Suurin piirilevyn koko: 510x460 mm

Minimi piirilevyn koko $\square$ 50x50mm

Piirilevyn paksuus $\square$ 0,5-4,5 mm

Levyn paksuus $\square$ 0,5-4mm

Komponenttien vähimmäiskoko: 0201

Tavallinen sirukoko-komponentti: 0603 ja suurempi

Komponentin enimmäiskorkeus $\square$ 15mm

Pienin lyijyväli: 0,3 mm

Minimi BGA-palloväli: 0,4 mm

Sijoituksen tarkkuus: +/- 0,03 mm